

Abstract

A tool (7) for handling a semiconductor material wafer (100) is designed to be used in an epitaxial growth station; the tool (7) comprises a disk (20) having an upper side (21) and a lower side (22), the lower side (22) being so shaped as to get in contact with the wafer (100) only along its edge (103); the disk (20) is provided internally with a suction chamber (24) that is in communication with the outside of the disk (20) through one or more suction holes (25) and in communication with a suction duct of an arm of a robot through a suction port (26); the disk (20) entirely covers the wafer (100) and the suction holes (25) open to the lower side (22) of the disk (20), whereby, when the wafer (100) is in contact with the lower side (22) of the disk (20), it can be held by the tool (7) through suction.